



Material Content Data Sheet



Sales Product Name	TLE9201SG			Issued		9. January 2019		
MA#	MA002790396							
Package	PG-DSO-12-17			Weight*		375.53 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.425	1.44	1.44	14447	14447
leadframe	inorganic material	phosphorus	7723-14-0	0.061	0.02		161	
	non noble metal	iron	7439-89-6	0.202	0.05		538	
	non noble metal	copper	7440-50-8	201.897	53.77	53.84	537635	538334
wire	non noble metal	copper	7440-50-8	1.484	0.40	0.40	3951	3951
encapsulation	organic material	carbon black	1333-86-4	0.310	0.08		825	
	plastics	epoxy resin	-	14.253	3.80		37954	
	inorganic material	silicondioxide	60676-86-0	140.362	37.38	41.26	373769	412548
leadfinish	non noble metal	tin	7440-31-5	3.243	0.86	0.86	8636	8636
plating	noble metal	silver	7440-22-4	2.024	0.54	0.54	5390	5390
solder	non noble metal	tin	7440-31-5	0.125	0.03		334	
	noble metal	silver	7440-22-4	0.157	0.04		417	
	non noble metal	lead	7439-92-1	5.987	1.59	1.66	15943	16694
*deviation	< 10%	Sum in total:			100.00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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